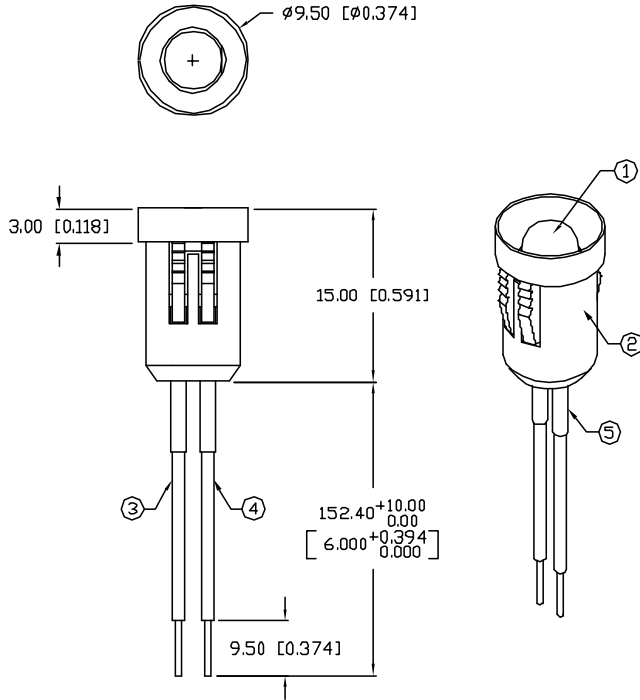


UNCONTROLLED DOCUMENT

PART NUMBER
SSI-LXR5020SID-150

REV.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		700		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:


- SSL-LX5093SID LED, CUT LEADS TO 4mm.
- SSH-RTF5020 HOLDER.
- ANODE LEAD: LXP-WST24RDTOC CUT 160 LONG, STRIP 3mm & 9.5mm.
- CATHODE LEAD: LXP-WST24BLTOC CUT 160 LONG, STRIP 3mm & 9.5mm.
- LXP-HEATSHRINK-2, (2 PCS.) 1/16" x 1/2" LONG.

PANEL CUTOUT: 8.05mm
PANEL THICKNESS: 0.6~2.8mm

CAUTION: PRESSURE SENSITIVE ASSEMBLY
AVOID APPLYING PRESSURE TO LED
DURING PANEL ASSEMBLY.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

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REV.	PART NUMBER SSI-LXR5020SID-150	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.		290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
T-5mm (T-1 3/4) ROUND PANEL INDICATOR LED, 636nm SUPER HIGH INTENSITY RED LED, RED DIFFUSED, WITH 6" WIRE LEADS.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: CT	CHECKED BY: APPROVED BY: DATE: 8.29.01 PAGE: 1 OF 1 SCALE: N/A